



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-02-04
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	IDO7*3702AAW	A	BO2A	2016-02-04
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85x3.9x1.52	8	gull wing	
Comment	Package for: O7 SO 08 .15 JEDEC; MDF valid for TS3702IDT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	IDO7*3702AAW					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.057	mg	supplier	die	Silicon (Si)	7440-21-3		1.012	mg	957427	12650
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	3784	50
				supplier	Passivation	Silicon Nitride	12033-89-5		0.003	mg	2838	38
				supplier	Passivation	Silicon Oxide	7631-86-9		0.019	mg	17975	238
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.019	mg	17975	238
Leadframe	Copper & its alloys	29.526	mg	supplier	alloy	Copper (Cu)	7440-50-8		27.902	mg	944998	348775
				supplier	alloy	Iron (Fe)	7439-89-6		0.656	mg	22218	8200
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.040	mg	1355	500
				supplier	alloy	Zinc (Zn)	7440-66-6		0.034	mg	1152	425
				supplier	metallization	Nickel (Ni)	7440-02-0		0.486	mg	16460	6075
				supplier	metallization	Palladium (Pd)	7440-05-3		0.031	mg	1050	388
				supplier	metallization	Gold (Au)	7440-57-5		0.013	mg	440	163
				supplier	metallization	Silver (Ag)	7440-22-4		0.364	mg	12328	4550
				supplier	glue	Silver (Ag)	7440-22-4		0.369	mg	911111	4613
				supplier	glue	acrylate	Proprietary		0.020	mg	49383	250
Die attach	Other Organic Materials	0.405	mg	supplier	glue	Methacrylate	Proprietary		0.016	mg	39506	200
				supplier	wire	Copper (Cu)	7440-50-8		0.072	mg	1000000	900
				supplier	glue	Proprietary						
Bonding wires	Other inorganic materials	0.072	mg	supplier	wire	Copper (Cu)	7440-50-8		0.072	mg	1000000	900
				supplier	glue	Proprietary						
Encapsulation	Other Organic Materials	48.940	mg	supplier	mold compound	Silica, vitreous	60676-86-0		42.382	mg	865999	529775
				supplier	mold compound	Epoxy Resin	Proprietary		3.670	mg	74990	45875
				supplier	mold compound	Phenol Resin	Proprietary		2.447	mg	50000	30588
				supplier	mold compound	Carbon black	1333-86-4		0.245	mg	5006	3063
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.196	mg	4005	2450